

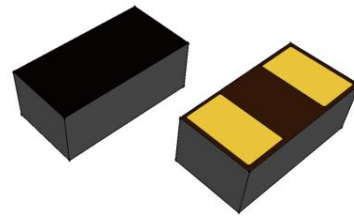
Surface Mount Polymeric ESD Suppressor

PE12VN50N-06

Description

PE12VN50N-06 polymeric ESD suppressor help protect sensitive electronic equipment against electrostatic discharge (ESD) without distorting data signals. This protection is a result of its ultra-low capacitance of only 0.05 pF (I/O to GND), and it can be used to help equipment to pass IEC61000-4-2 level 4 test (15KV air, 8KV contact discharge).

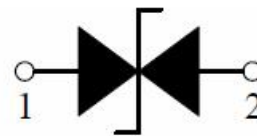
(EIA Size) 0201



Features

- ◆ Ultra low capacitance:5pF(typ.).
- ◆ Fast response time(<1ns).
- ◆ Low leakage current.
- ◆ Bi-directional, single line protection.
- ◆ IEC61000-4-2(Contact): 8KV, IEC61000-4-2(Air) :15KV.

Equivalent Circuit



Applications

- ◆ Smart Phone/Mobile Internet Device.
- ◆ Laptop/Desktop Computer.
- ◆ Antennas (Cell phones, GPS...).
- ◆ USB 3.0,USB 3.1 and high speed interface.

General Characteristics

Parameter	Max	Unit
Contact Discharge Voltage Per IEC61000-4-2	8	KV
Air Discharge Voltage Per IEC61000-4-2	15	KV
Operating Temperature	-55 to +125	℃
Storage Temperature	-40 to +85	℃

Surface Mount Polymeric ESD Suppressor

PE12VN50N-06

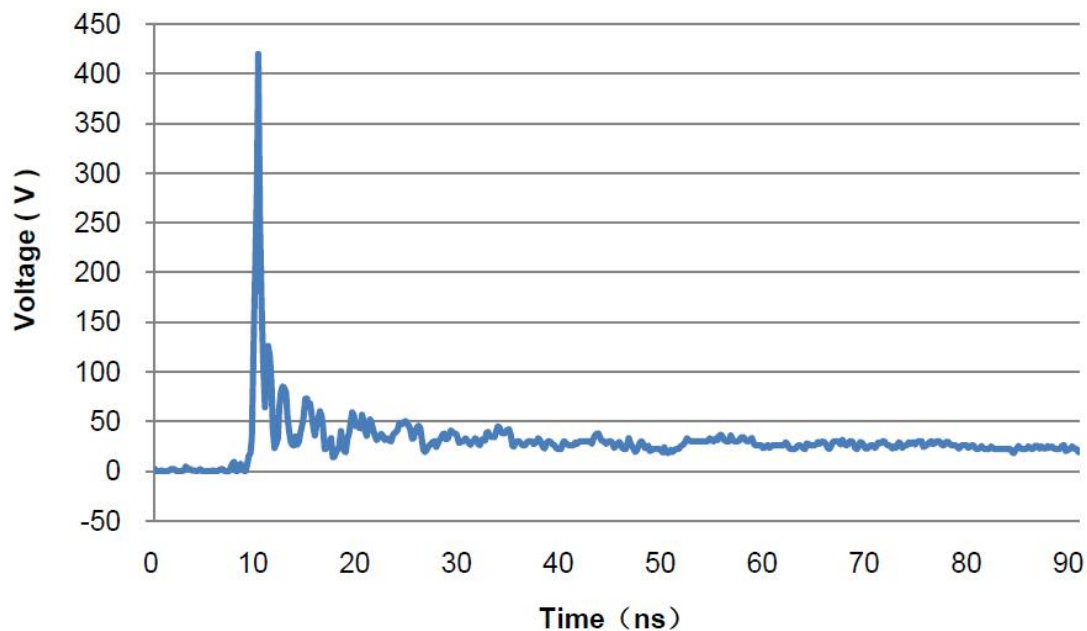
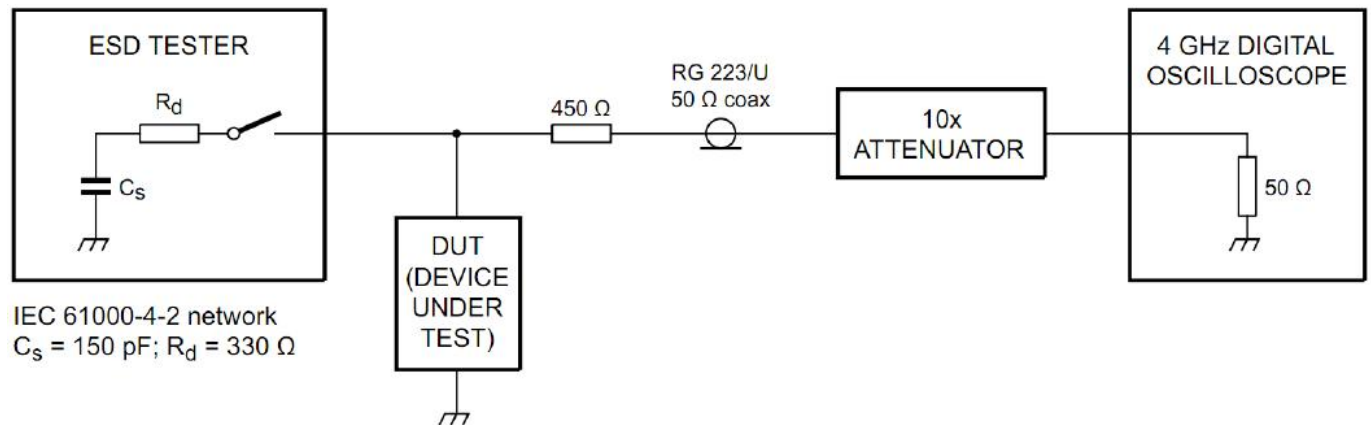
Electrical Characteristics (T_A = 25°C)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Continuous Operating Voltage	V _{DC}	--	--	--	12	V
Trigger Voltage	V _T	IEC61000-4-2 8KV contact discharge	--	450	--	V
Clamping Voltage	V _C	IEC61000-4-2 8KV contact discharge	--	40	--	V
Leakage Current	I _L	DC 12V shall be applied on component	--	--	10	nA
Capacitance	C _P	Measured at 10MHz	--	5	--	pF
ESD Pulse Withstand	Pulses	IEC61000-4-2 8KV contact discharge	1000	--	--	--

Note:

Trigger and clamping voltage are measured per IEC 61000-4-2, 8KV contact discharge method.

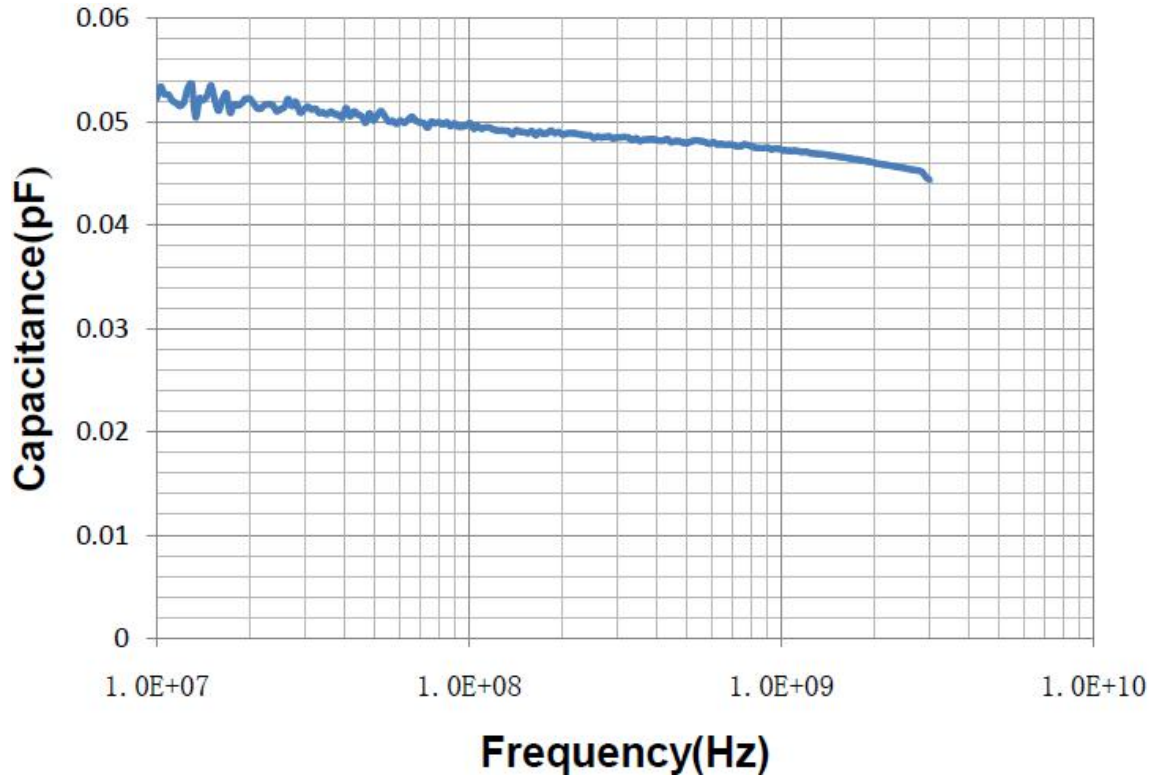
Typical ESD Response (IEC 61000-4-2, 8KV contact discharge)



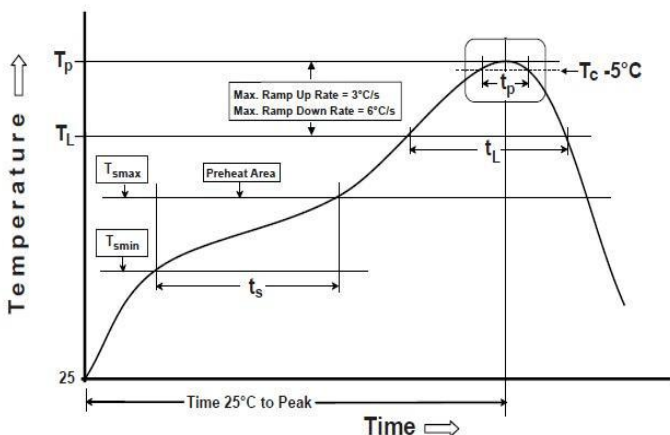
Surface Mount Polymeric ESD Suppressor

PE12VN50N-06

Typical Device Capacitance VS. Frequency



Soldering Parameters



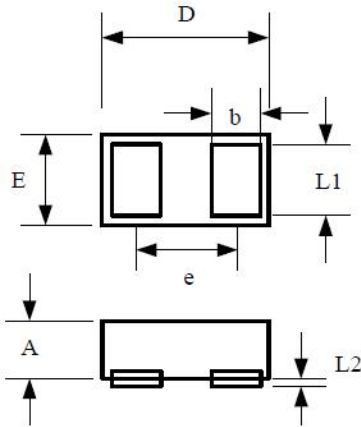
Profile Feature		Pb-Free Assembly
Pre Heat	Temperature Min (T_{smin})	150°C
	Temperature Max (T_{smax})	200°C
	Time (T_s) from (T_{smin} to T_{smax})	60-120 seconds
Ramp-up Rate (T_L to T_P)		3°C/second max.
Liquidus Temperature (T_L)		217°C
Time (t_L) maintained above T_L		60-150 seconds
Peak Package Body Temperature (T_P)		260 ^{+0/-5} °C
Time (t_p)* within 5°C of the Specified Classification Temperature (T_c)		30* seconds
Ramp-down Rate (T_P to T_L)		6°C/second max.
Time 25°C to peak Temperature		8 minutes Max
* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.		

Surface Mount Polymeric ESD Suppressor

PE12VN50N-06

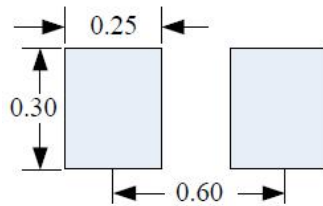
Package Dimension

Package Outline



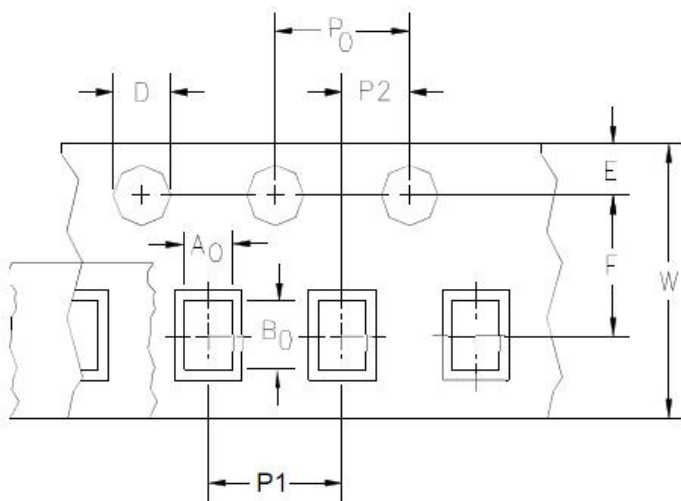
Dimension	Unit: Millimeters	
	Min.	Max.
A	0.25	0.40
b	0.15	0.20
D	0.50	0.70
E	0.25	0.35
e	0.45 BSC	
L1	0.20	0.30
L2	0.00	0.05

Recommended Solder Pad Footprint



Sizes in mm

Taping Specification (Unit: mm)

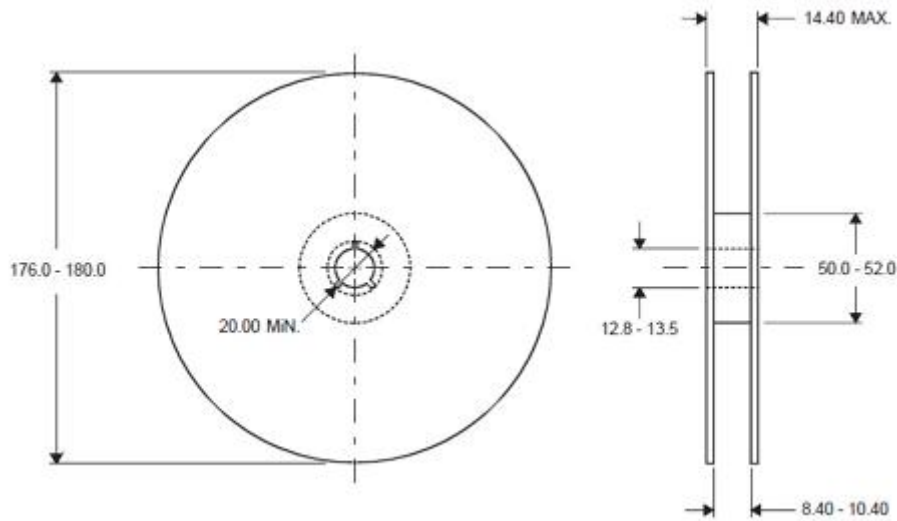


Dimension	Typical
A0	0.38
B0	0.68
D	1.55
P0	4.00
P1	2.00
P2	2.00
E	1.75
F	3.50
W	8.00

Surface Mount Polymeric ESD Suppressor

PE12VN50N-06

Taping Specification (Unit: mm) (Continue)



Sizes in mm

Order Information

Device	Package	Net Weight	Carrier	Quantity
PE12VN50N-06	(EIA Size) 0201	0.12 mg	Tape & Reel	15,000pcs/reel